

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	12468	(smart-card or (smart adj card) or smartcard) near3 (chip or device)	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/22 18:01
L2	201735	(circuit or chip) near3 structur\$3	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/22 18:01
L3	58	L1 same L2	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/22 18:01
L4	17	L3 and (metal and diffusion)	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/22 18:01
L9	1226210	(protective or security or (smartcard or smart-card or (smart adj card)))	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/22 18:28
L10	205905	(coating or filling) same insulat\$4	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/22 18:29
L11	36091	L9 and L10	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/22 18:29
L12	1065	(add\$4 or additional or insert\$4 or plac\$6) near5 (circuit adj function)	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/22 18:30
L13	12	L12 and L11	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/22 18:31

L14	2	L13 and til\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/22 18:31
L15	312348	(add\$4 or additional or insert\$4 or plac\$6) near5 (function)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/22 18:35
L16	1600	L15 and L11	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/22 18:35
L17	587	L16 and (routing or wiring)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/22 18:36
L18	584875	conductive same (tile or structure or layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/22 18:38
L19	433	L17 and L18	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/22 18:38
L20	0	L19 and diffusion	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/22 18:40
L21	0	L17 and diffusion	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/22 18:40
L22	70662	L9 and diffusion	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/22 18:41
L23	7206	L10 and L22	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/22 18:41

L24	465	L15 and L23	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/22 18:41
L25	214	L24 and (routing or wiring)	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/22 18:42
L26	159	L18 and L25	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/22 18:42
L27	2	("20030127709" or ("6613661")).PN.	US_PGPUB; USPAT; JPO	OR	OFF	2008/06/22 18:50
L28	2	L27 and (security or protective or smartcard or smart-card or (smart adj card))	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/22 18:51
L29	2	L28 and insulat\$4	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/22 18:52
L30	2	L29 and additional	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/22 18:52
S1	12457	(smart-card or (smart adj card) or smartcard) near3 (chip or device)	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/20 17:20
S2	1870	S1 and (wafer or substrate)	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/20 17:21
S3	823	S2 and silicon	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/20 17:21
S4	476	S3 and insulat\$5	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/20 17:22

S5	308	S4 and fill\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/20 17:22
S6	294	S5 and contact\$2	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/20 17:22
S7	271	S6 and function\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/20 17:23
S8	51627	active near3 structure	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/20 17:23
S9	51	S7 and diffusion	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/20 17:23
S10	43	S9 and (rout\$4 or wir\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/20 17:24
S11	6	S10 and node	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/20 17:24
S12	41	S10 and circuit	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/20 17:24
S13	5741643	structur\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/20 17:31
S14	473	S1 same S13	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/20 17:32

S15	201542	(circuit or chip) near3 structur\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/20 17:35
S16	473	S1 same S14	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/20 17:35
S17	0	S1 same "L154"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/20 17:35
S18	58	S1 same S15	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/20 17:35
S19	17	S18 and (metal and diffusion)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/20 17:35
S20	4	S19 and insulat\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/20 17:35
S21	402078	(security-sensitive or security or securitized)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/20 17:40
S22	2491	S1 same S21	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/20 17:40
S23	402023	(security-sensitive or security)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/20 17:40
S24	7499	S1 and S23	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/20 17:40

S25	117418	circuit near2 structure	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/20 17:40
S26	139	S24 and S25	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/20 17:41
S27	1452	filling adj structur\$3	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/20 17:42
S28	3	S26 and S27	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/20 17:42
S29	3	S27 and S1	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/20 17:42

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